

PART INFORMATION	
Mfg Item Number	KCUDSP56321VL200
Mfg Item Name	MAPBGA 196 15*15*0.8P1.0
SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-06-09
Response Document ID	5268K11034D017A1.10
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com
DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	
MANUFACTURING	
Mfg Item Number	KCUDSP56321VL200
Mfg Item Name	MAPBGA 196 15*15*0.8P1.0
Version	ALL
Weight	0.619200
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.</p>
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
<p>List of Freescale Accepted Exemptions</p> <p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>	

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart	SubPart%	ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0089	Plastics/polymers	Proprietary Material-Other Epoxy resins	-	0.000675	g	75000	7.5		1078	0.1078
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5	0.00178	g	200000	20		2874	0.2874
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-	0.000675	g	75000	7.5		1078	0.1078
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-	0.00178	g	200000	20		2874	0.2874
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0	0.004005	g	450000	45		6468	0.6468
Solder Balls - Lead Free	0.0985					g					
Solder Balls - Lead Free		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0	0.0000069	g	7	0.0007		1	0.0001
Solder Balls - Lead Free		Arsenic/Arsenic Compounds	Arsenic	7440-38-2	0.0000069	g	7	0.0007		1	0.0001
Solder Balls - Lead Free		Bismuth/Bismuth Compounds	Bismuth	7440-69-9	0.0000049	g	5	0.0005		0	0
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8	0.0006895	g	7000	0.7		1113	0.1113
Solder Balls - Lead Free		Metals	Iron, metal	7439-89-6	0.0000177	g	18	0.0018		2	0.0002
Solder Balls - Lead Free		Lead/Lead Compounds	Lead	7439-92-1	0.0000052	g	56	0.0056		8	0.0008
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4	0.0037036	g	37600	3.76		5981	0.5981
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5	0.09409774	g	955307	95.5307		151966	15.1966
Silicon Semiconductor Die	0.04	Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-	0.0008	g	20000	2		1291	0.1291
Silicon Semiconductor Die		Glass	Silicon, doped	-	0.0392	g	980000	98		63307	6.3307
Die Encapsulant, Halogen-free	0.3168					g					
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (2674)	68891-46-3	0.0001584	g	500	0.05		255	0.0255
Die Encapsulant, Halogen-free		Metals	Proprietary Material-Other aluminum compounds	-	0.003168	g	10000	1		5116	0.5116
Die Encapsulant, Halogen-free		Plastics/polymers	Other Epoxy resins	-	0.00792	g	25000	2.5		12790	1.279
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other Epoxy resins	-	0.00792	g	25000	2.5		12790	1.279
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.001584	g	5000	0.5		2558	0.2558
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other phenolic resins	-	0.012672	g	40000	4		20465	2.0465
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9	0.06336	g	200000	20		102325	10.2325
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0	0.2200176	g	694500	69.45		355344	35.5344
Organic Substrate	0.1514					g					
Organic Substrate		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (2674)	68891-46-3	0.00352141	g	23259	2.3259		5687	0.5687
Organic Substrate		Metals	Barium sulfate	7727-43-7	0.00614245	g	40571	4.0571		9918	0.9918
Organic Substrate		Metals	Copper, metal	7440-50-8	0.07375753	g	487170	48.717		119117	11.9117
Organic Substrate		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl diglycidyl ether	85954-11-6	0.00066177	g	4371	0.4371		1068	0.1068
Organic Substrate		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5	0.03496919	g	229169	22.9169		56033	5.6033
Organic Substrate		Metals	Gold, metal	7440-57-5	0.00033505	g	2213	0.2213		541	0.0541
Organic Substrate		Solvents, additives, and other materials	Silicon	7440-21-3	0.00007979	g	527	0.0527		128	0.0128
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0	0.0034006	g	22461	2.2461		5491	0.5491
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3	0.02102068	g	138842	13.8842		33948	3.3948
Organic Substrate		Plastics/polymers	Other acrylic resins	-	0.00467084	g	30851	3.0851		7543	0.7543
Organic Substrate		Plastics/polymers	Other acrylic/epoxy resin mixture	-	0.00311369	g	20566	2.0566		5028	0.5028
Bonding Wire, PdCu	0.0036					g					
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8	0.0035316	g	981000	98.1		5703	0.5703
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5	0.0000036	g	1000	0.1		5	0.0005
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3	0.0000648	g	18000	1.8		104	0.0104

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/KCUDSP56321VL200_IPC1752_v11.xml

http://www.freescale.com/mcds/KCUDSP56321VL200_IPC1752A.xml